SiE818DF Vishay Siliconix

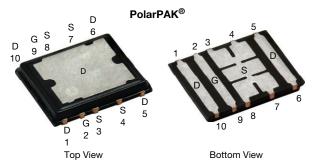
RoHS

COMPLIANT HALOGEN

FREE

www.vishay.com

N-Channel 75 V (D-S) MOSFET



Top surface is connected to pins 1, 5, 6, and 10

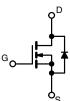
PRODUCT SUMMARY				
V _{DS} (V)	75			
$R_{DS(on)}$ max. (Ω) at V_{GS} = 10 V	0.0095			
$R_{DS(on)}$ max. (Ω) at V_{GS} = 4.5 V	0.0125			
Q _g typ. (nC)	33			
I _D (A) ^a (package limit)	60			
I _D (A) ^a (silicon limit)	79			
Configuration	Single			

FEATURES

- TrenchFET[®] power MOSFET
- Ultra low thermal resistance using top-exposed PolarPAK[®] package for double-sided cooling
- Leadframe-based encapsulated package
 Die not exposed
 Same layout regardless of die size
- Low Q_{ad}/Q_{as} ratio helps prevent shoot-through
- 100 % R_{α} and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Primary side switch
- Half-bridge
- Synchronous rectification



N-Channel MOSFET

ORDERING INFORMATION

Package	PolarPAK
Lead (Pb)-free	SiE818DF-T1-E3
Lead (Pb)-free and halogen-free	SiE818DF-T1-GE3

ABSOLUTE MAXIMUM RATING	3 $(I_A = 25^{-1}C, L)$	iniess otherwise	noted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	75	V	
Gate-source voltage		V _{GS}	± 20		
Continuous drain current (T _J = 150 °C)	T _ 25 °C		60 ^a (package Limit)		
	T _C = 25 °C		79 (silicon Limit)		
	T _C = 70 °C	I _D	60 ^a		
	T _A = 25 °C		16 ^{b, c}		
	T _A = 70 °C	1 -	12.9 ^{b, c}	А	
Pulsed drain current		I _{DM}	80		
Continuous source-drain diode current	T _C = 25 °C		60 ^a		
	T _A = 25 °C	I _S	4.3 ^{b, c}		
Single pulse avalanche current	L = 0.1 mH	I _{AS}	50		
Avalanche energy	L = 0.1 mH	E _{AS}	125	mJ	
Maximum power dissipation	T _C = 25 °C		125		
	T _C = 70 °C		80		
	T _A = 25 °C	P _D	5.2 ^{b, c}	W	
	T _A = 70 °C	1	3.3 ^{b, c}		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) d, e		Ĭ	260	-0	

Notes

a. Package limited

b. Surface mounted on 1" x 1" FR4 board

c. t = 10 s

d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PolarPAK is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

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THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient a, b	$t \le 10 s$	R _{thJA}	20	24	
Maximum junction-to-case (drain top)	Steady state	R _{thJC} (drain)	0.8	1	°C/W
Maximum junction-to-case (source) a, c	Sleady state	R _{thJC} (source)	2.2	2.7	

Notes

a. Surface mounted on 1" x 1" FR4 board

b. Maximum under steady state conditions is 68 °C/W

c. Measured at source pin (on the side of the package)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static	- I				1	
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	75	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$		-	78	-	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	_	-7.1	-	mV/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.5	2.1	3	V
Gate-source leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	± 100	nA
Zero gate voltage drain current	_	$V_{DS} = 75 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	1	- μΑ
	IDSS	V _{DS} = 75 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10	
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	25	-	-	Α
	_ ` `	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 16 \text{ A}$	-	0.0078	0.0095	Ω
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 14 \text{ A}$	-	0.0103	0.0125	
Forward transconductance ^a	g _{fs}	V _{DS} = 20 V, I _D = 16 A	-	50	-	S
Dynamic ^b	•		·			•
Input capacitance	C _{iss}	V _{DS} = 38 V, V _{GS} = 0 V, f = 1 MHz	-	3200	-	pF
Output capacitance	C _{oss}		-	330	-	
Reverse transfer capacitance	C _{rss}		-	170	-	
Total gata abarga	0	$V_{DS} = 38 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 16 \text{ A}$	-	63	95	nC
Total gate charge	Qg	$V_{DS} = 38 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 16 \text{ A}$	-	33	50	
Gate-source charge	Q _{gs}		-	11	-	
Gate-drain charge	Q _{gd}		-	17	-	
Gate resistance	Rg	f = 1 MHz	-	0.95	1.5	Ω
Turn-on delay time	t _{d(on)}		-	30	45	
Rise time	t _r	$V_{DD} = 38 \text{ V}, \text{ R}_{L} = 3.8 \Omega,$	-	150	225	
Turn-off delay time	t _{d(off)}	$I_D \cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω	-	40	60	
Fall time	t _f		-	15	25	ne
Turn-on delay time	t _{d(on)}		-	15	25	ns -
Rise time	t _r	$V_{DD} = 38 \text{ V}, \text{ R}_{L} = 3.8 \Omega,$	-	15	25	
Turn-off delay time	t _{d(off)}	$I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω	-	40	60	
Fall time	t _f		-	10	15	
Drain-Source Body Diode Characterist	ics		-	1	1	-
Continuous source-drain diode current	۱ _S	$T_{C} = 25 \ ^{\circ}C$	-	-	60	А
Pulse diode forward current ^a	I _{SM}		-	-	80	~
Body diode voltage	V _{SD}	I _S = 10 A	-	0.8	1.2	V
Body diode reverse recovery time	t _{rr}	I _F = 10 A, di/dt = 100 A/μs, T _J = 25 °C	-	100	150	ns
Body diode reverse recovery charge	Q _{rr}		-	345	520	nC
Reverse recovery fall time	t _a		-	75	-	
Reverse recovery rise time	t _b		_	25	_	ns

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %

b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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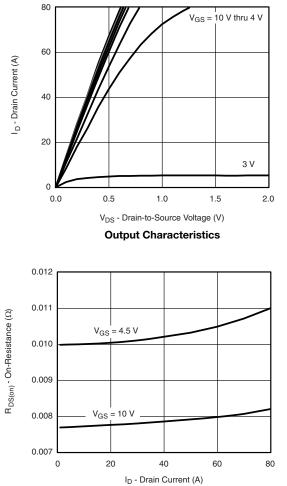
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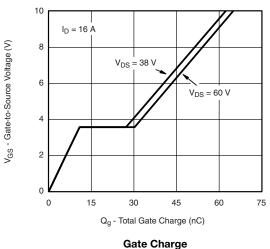
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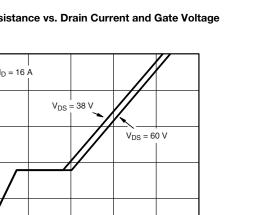
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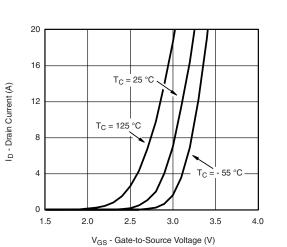
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



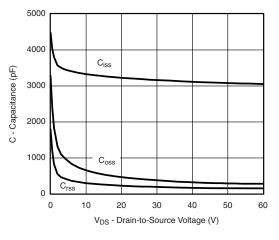
On-Resistance vs. Drain Current and Gate Voltage



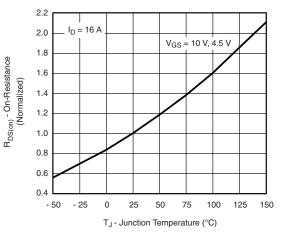




Transfer Characteristics



Capacitance



On-Resistance vs. Junction Temperature

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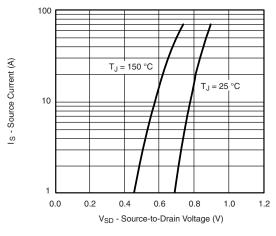
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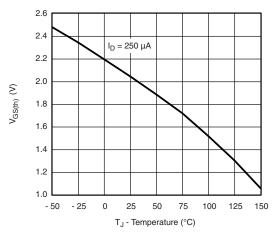
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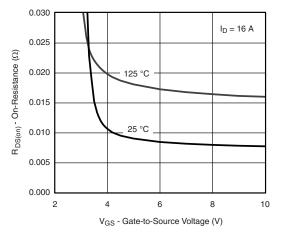
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



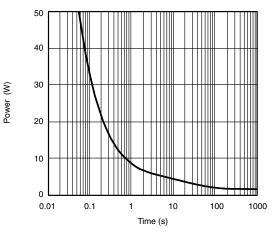
Source-Drain Diode Forward Voltage



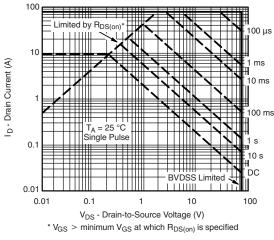




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient

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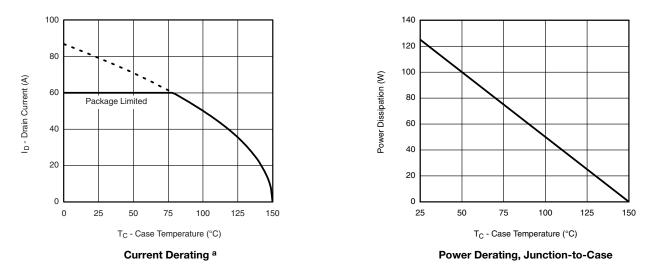
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



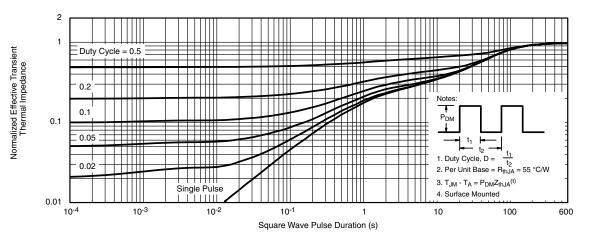
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

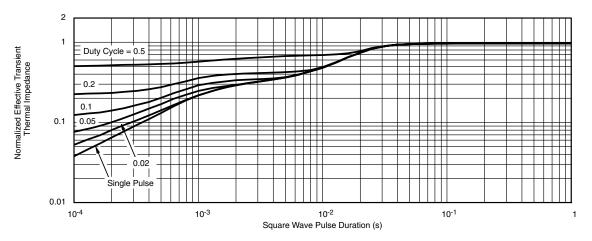


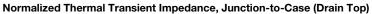
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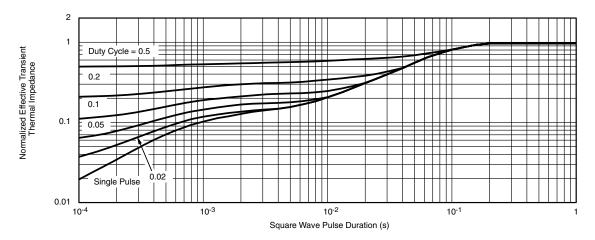
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient







Normalized Thermal Transient Impedance, Junction-to-Source

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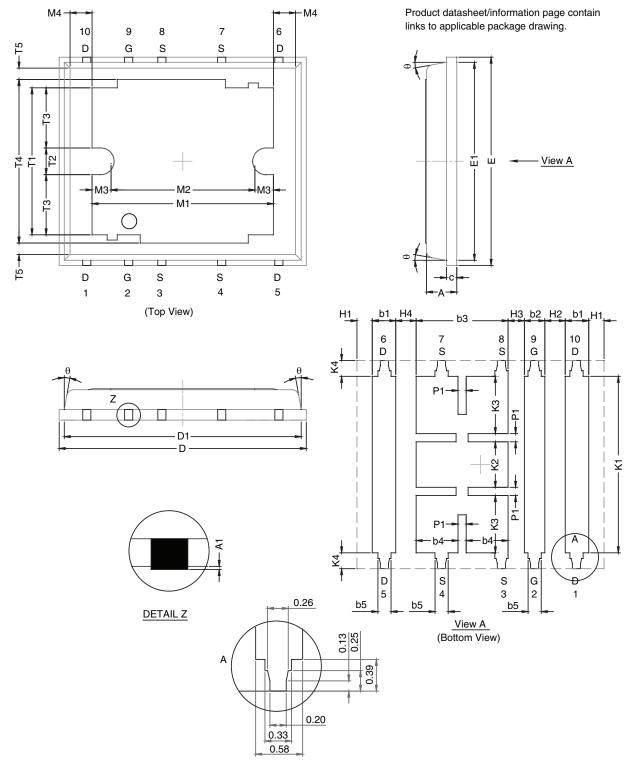
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Package Information

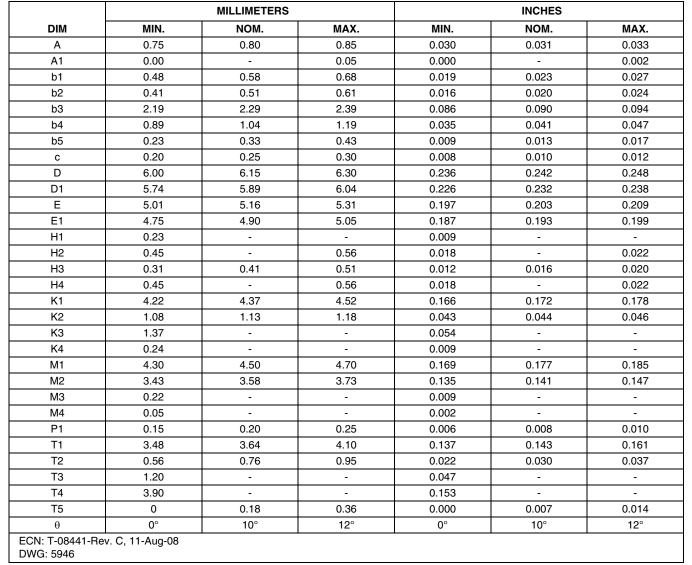
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POLARPAK™ OPTION L



Package Information

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Notes

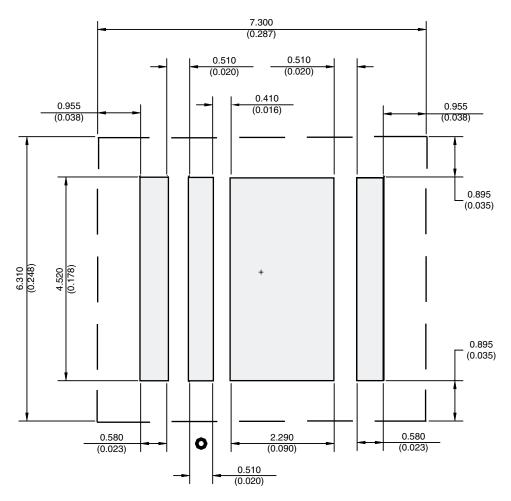
Millimeters govern over inches.



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RECOMMENDED MINIMUM PADS FOR PolarPAK® Option L and S



Recommended Minimum for PolarPAK Option L and S Dimensions in mm/(Inches) No External Traces within Broken Lines Dot indicates Gate Pin (Part Marking)

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